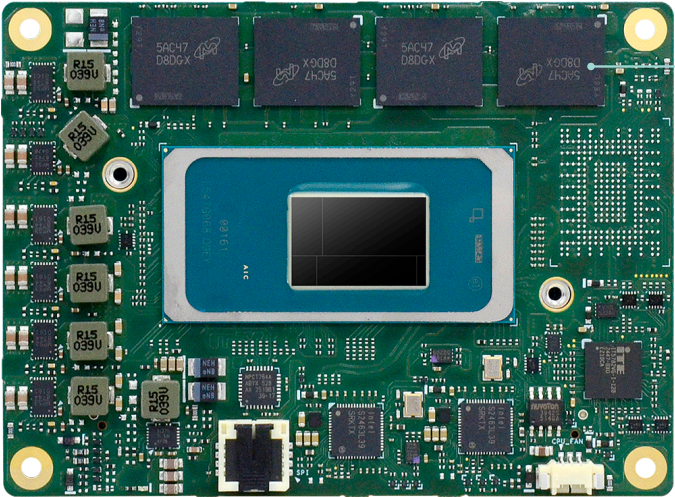


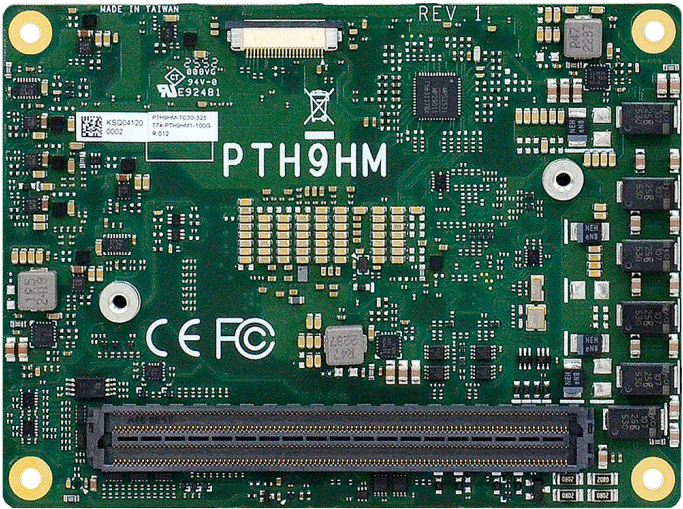
PTH9HM

Intel® Core™ Ultra Series 3 Processors
COM HPC® Mini



LPDDR5

Front View



Bottom View

KEY FEATURES



LPDDR5

UP to 64GB LPDDR5x-8533 memory down



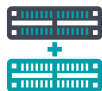
4K High Resolution

Supports 8K / 4K resolution



Multiple Displays

2 DDI, 1 eDP



Multiple Expansion

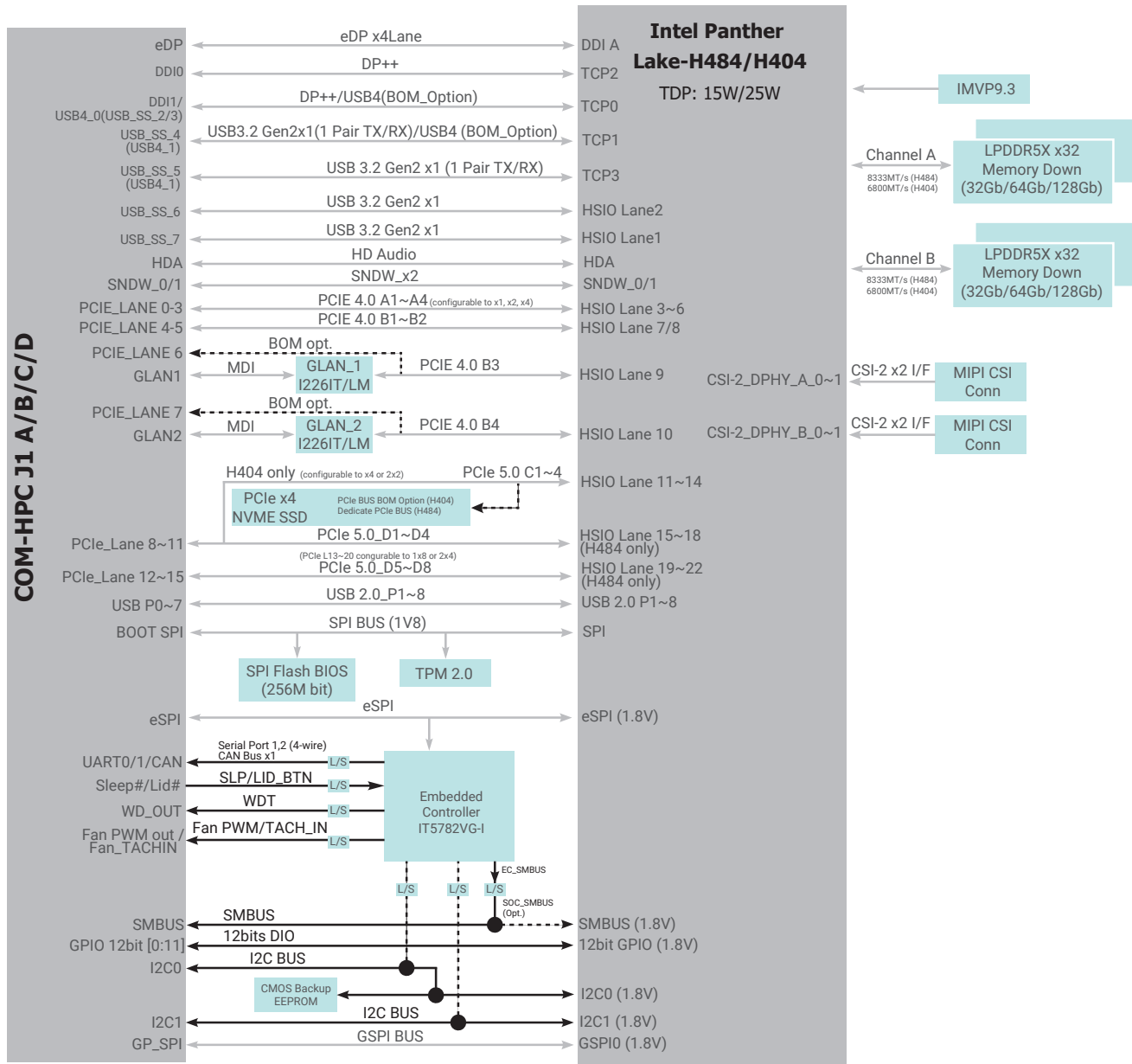
Up to 8 PCIe x1 (Gen4),
1 PCIe x4 (Gen5)
or 2 PCIe x4 (selected sku)

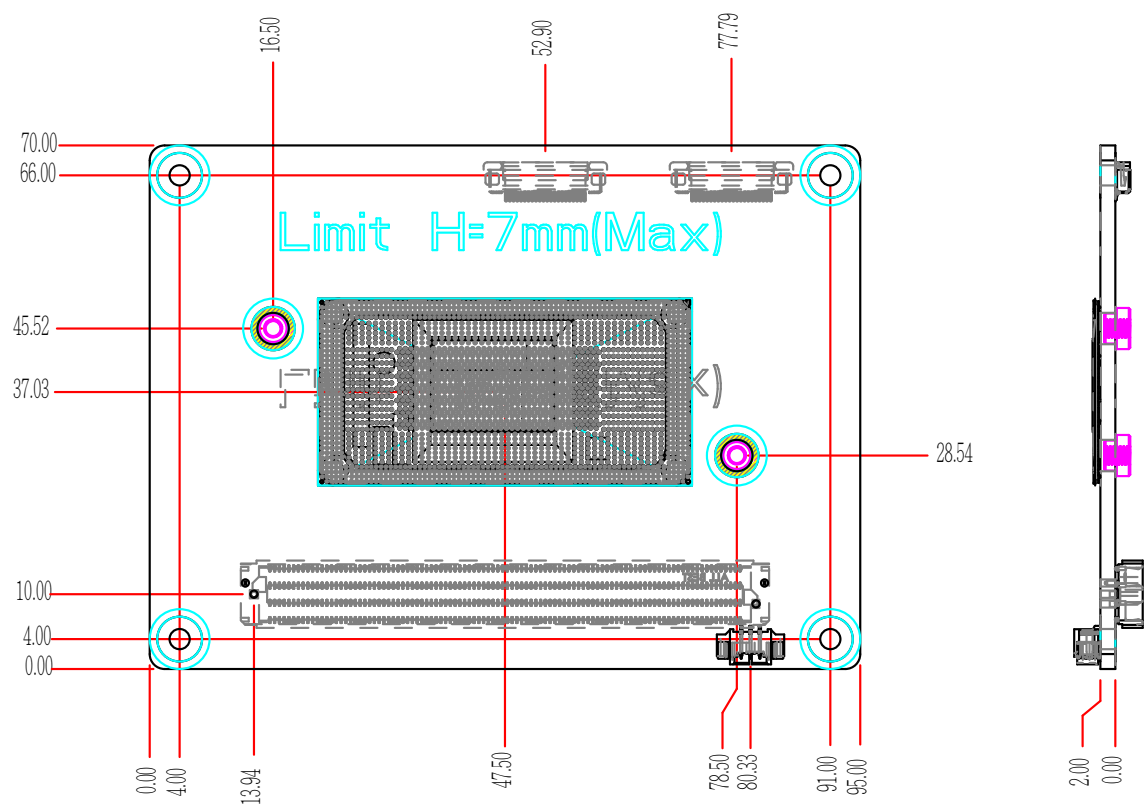


RICH I/O

2 Intel 2.5GbE,
4 USB 3.2

BLOCK DIAGRAM





SPECIFICATION

SYSTEM	Processor	Intel® Core™ Ultra Series 3 Processor Intel® Core™ Ultra 7 358H, 16C, 4.8 GHz, 18M Cache, 25W Intel® Core™ Ultra 7 366HRE, 16C, 4.8 GHz, 18M Cache, 25W Intel® Core™ Ultra 7 356H, 16C, 4.7 GHz, 18M Cache, 25W Intel® Core™ Ultra 5 336HRE, 12C, 4.6 GHz, 18M Cache, 25W Intel® Core™ Ultra 5 325, 8C, 4.5 GHz, 12M Cache, 25W
	Memory	Up to 64GB LPDDR5x memory down w/max. 8533 MT/s on selected skus (IBECC support)
	BIOS	AMI BIOS
GRAPHICS	Controller	Intel® ARC™ graphics or Intel® graphics
	Feature	DX12, Open GL 4.6, Vulkan 1.2 HW Decode: HEVC/VP9/AV1/AVC/H.265/MJPEG HW Encode: HEVC/VP9/AV1/AVC/H.265/MJPEG
	Display	2 x DDI 1 x eDP
EXPANSION	Interface	Up to 8 x PCIe x1 (Gen4) + 1 x PCIe x4 (Gen 5) or 1 x PCIe x8 (Gen5)(BIOS Default), configurable as 2 x PCIe x4 (Gen5) upon request on selected sku 3 x I2C 1 x SMBus 1 x SPI 2 x UART 1 x GP_SPI
AUDIO	Audio Codec	HD Audio
ETHERNET	Controller	2 x Intel® I226 series (10/100/1000/2500Mbps), co-lay 2 x PCIe x1 (available upon request)
I/O	USB	Up to 2 x USB 4.0 (co-lay with DDI and USB3, available upon request) 4 x USB 3.2 Gen.2 (2 x Co-lay with USB4) 8 x USB 2.0
	NVMe SSD	1 x 128GB/256GB/512GB/1024GB on board SSD (available upon request)
	DIO	1 x 12-bit DIO
WATCHDOG TIMER	Output & Interval	System Reset, Programmable via Software from 1 to 255 Seconds
SECURITY	TPM	TPM 2.0
POWER	Type	8.5~20V DC
	Consumption	TBD
OS SUPPORT	Microsoft	Windows 11 IoT Enterprise 64-bit
	Linux	Linux
ENVIRONMENT	Temperature	Operating: -40 to 85°C Storage: -40 to 85°C
	Humidity	Operating: 10 to 90% RH Storage: 10 to 90% RH
	MTBF	TBD
MECHANICAL	Dimensions	COM HPC® Mini 95mm (3.74") x 70mm (2.76")
	Compliance	PICMG COM HPC® R1.3, Mini
STANDARDS AND CERTIFICATIONS	Certification	CE, FCC, RoHS

ORDERING INFORMATION

Model Name	P/N	Processor	Memory	NVME SSD	DDI/USB4	LAN/PCIe	USB3/USB4	Thermal	Temp.
PTH9HM-TC30-358H	770-PTH9HM1-100G	Ultra 7 358H	32GB	NA	DDI	LAN	USB3	Cooler	-40~85°C
PTH9HM-TC60-366HRE	770-PTH9HM1-200G	Ultra 7 366HRE	64GB						
PTH9HM-TC60-356H	770-PTH9HM1-300G	Ultra 7 356H	64GB						
PTH9HM-TC30-336HRE	770-PTH9HM1-400G	Ultra 5 336HRE	32GB						
PTH9HM-TC10-325	770-PTH9HM1-500G	Ultra 5 325	16GB						

PACKING LIST

• Cooler	TBD
• CPU block	A71-210414-000G
• Thermal Grease	912-077621-000G

OPTIONAL ITEMS

• COM337 Carrier Board	770-COM3371-000G
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